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This document was prepared by the InterNational Committee for Information Technology Standards (INCITS) (as INCITS 543-2019) and drafted in accordance with its editorial rules. It was assigned to Joint Technical Committee ISO/IEC JTC 1, *Information technology*, and adopted under the "fast-track procedure".

A list of all parts in the ISO/IEC 14165 series can be found on the ISO website.

Any feedback or questions on this document should be directed to the user's national standards body. A complete listing of these bodies can be found at www.iso.org/members.html.

Contents

List of Tables

List of Figures

Foreword (This foreword is not part of American National Standard INCITS 543-2019.)

This standard was developed by Task Group T11.2 of Accredited Standards Committee INCITS during 2016, 2017, and 2018. The standards approval process will be started in 2018. This document includes annexes that are informative and are not considered part of the standard.

Requests for interpretation, suggestions for improvements or addenda, or defect reports are welcomed. They should be sent to the INCITS Secretariat, Information Technology Industry Council, 700 K Street NW, Suite 600, Washington DC 20001.

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Fibre Channel – Physical Interface-7 (FC-PI-7)

1 Scope

This standard describes the physical interface portions of high performance optical link variants that support the higher level Fibre Channel protocols including FC-FS-4 (reference [1]) and FC-FS-5 (reference [2]).

FC-PI-7 specifies 64GFC. 32GFC and 128GFC are described in FC-PI-6 (reference [3]) and FC-PI-6P (reference [4]), respectively.16GFC, 8GFC and 4GFC are described in FC-PI-5 (reference [5]).

2 Normative references

2.1 General

The following standards contain provisions that, through reference in this text, constitute provisions of this standard. At the time of publication, the editions indicated were valid. Standards are subject to revision, and parties to agreements based on this standard are encouraged to investigate the possibility of applying the most recent editions of the following list of standards. Members of IEC and ISO maintain registers of currently valid International Standards.

Copies of the following documents can be obtained from ANSI: Approved ANSI standards, approved and draft international and regional standards (ISO, IEC), and other approved standards (including JIS and DIN).

2.2 Normative references

2.2.1 Approved references

[1] INCITS 488-2016, FC-FS-4, Fibre Channel Framing and Signaling - 4

[2] INCITS 545-2018, FC-FS-5, Fibre Channel Framing and Signaling - 5

[3] INCITS 512-2015, FC-PI-6, Fibre Channel Physical Interfaces - 6

[4] INCITS 533-2016, FC-PI-6P, Fibre Channel Physical Interfaces - 6P

[5] INCITS 479-2011, FC-PI-5, Fibre Channel Physical Interfaces - 5

[6] INCITS TR-46-2011, FC-MSQS, Fibre Channel Methodologies for Signal Quality Specification

[7] INCITS TR-50-2014, FC-MSQS-2, Fibre Channel Methodologies for Signal Quality Specification 2

[8] IEC 61280-1-3, Fiber optic communication subsystem basic test procedures - Part 1-3: Test procedures for general communication subsystems - Central wavelength and spectral width measurement

[9] **IEC 60793-2-10,** Optical fibers - Part 2-10: Product specifications - Sectional specification for category A1 multimode fibers

[10] **IEC 60793-2-50,** Optical fibers - Part 2-50: Product specifications - Sectional specification for class B single-mode fibers

[11] **IEC 60825-1,** Safety of laser products - Part 1: Equipment classification and requirements, latest edition.

[12] **IEC 60825-2,** Safety of laser products - Part 2: Safety of optical fiber communication systems, latest edition.

[13] **TIA-492AAAC,** Detail Specification for 850-nm Laser-Optimized, 50-μm Core Diameter/125-μm Cladding Diameter Class Ia Graded-Index Multimode Optical Fibers

[14] **TIA-492AAAD,** Detail Specification for 850-nm Laser-Optimized, 50-μm Core Diameter/125-μm Cladding Diameter Class Ia Graded-Index Multimode Optical Fibers Suitable for Manufacturing OM4 Cabled Optical Fiber

[15] **TIA-492AAAE,** Detail Specification for 50-μm Core Diameter/125-μm Cladding Diameter Class 1a Graded-Index Multimode Optical Fibers with Laser-Optimized Bandwidth Characteristics Specified for Wavelength Division Multiplexing

[16] **IEEE 802.3™-2018,** IEEE Standard for Ethernet

[17] **OIF-CEI-04.0,** Clause 21 CEI-56G-LR PAM4 Long Reach Interface

2.2.2 References under development

At the time of publication, the following referenced standards were still under development. For information on the current status of the documents, or regarding availability, contact the relevant standards body or other organization as indicated.

[18] **IEEE 802.3cd** 50Gb/s and 200 Gb/s Ethernet Task Force

